Features

- Fast Read Access Time 45 ns
- Low-Power CMOS Operation
 - 100 µA Max Standby
 - 20 mA Max Active at 5 MHz
- JEDEC Standard Packages
 - 28-lead PDIP
 - 32-lead PLCC
 - 28-lead TSOP and SOIC
- 5V ± 10% Supply
- High-Reliability CMOS Technology
 - 2.000V ESD Protection
 - 200 mA Latchup Immunity
- Rapid Programming Algorithm 100 µs/Byte (Typical)
- CMOS and TTL Compatible Inputs and Outputs
- Integrated Product Identification Code
- Industrial and Automotive Temperature Ranges
- Green (Pb/Halide-free) Packaging Option

1. Description

The AT27C512R is a low-power, high-performance 524,288-bit one-time programmable read-only memory (OTP EPROM) organized 64K by 8 bits. It requires only one 5V power supply in normal read mode operation. Any byte can be accessed in less than 45 ns, eliminating the need for speed reducing WAIT states on high-performance microprocessor systems.

Atmel's scaled CMOS technology provides high-speed, lower active power consumption, and significantly faster programming. Power consumption is typically only 8 mA in Active Mode and less than 10 μ A in Standby.

The AT27C512R is available in a choice of industry-standard JEDEC-approved one-time programmable (OTP) plastic PDIP, PLCC, SOIC, and TSOP packages. All devices feature two-line control ($\overline{\text{CE}}$, $\overline{\text{OE}}$) to give designers the flexibility to prevent bus contention.

With 64K byte storage capability, the AT27C512R allows firmware to be stored reliably and to be accessed by the system without the delays of mass storage media.

Atmel's AT27C512R has additional features to ensure high quality and efficient production use. The Rapid Programming Algorithm reduces the time required to program the part and guarantees reliable programming. Programming time is typically only 100 μ s/byte. The Integrated Product Identification Code electronically identifies the device and manufacturer. This feature is used by industry-standard programming equipment to select the proper programming algorithms and voltages.



512K (64K x 8) OTP EPROM

AT27C512R

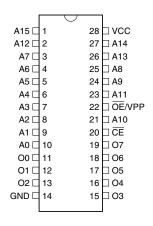




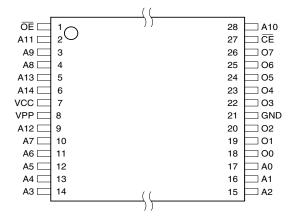
2. Pin Configurations

Pin Name	Function
A0 - A15	Addresses
00 - 07	Outputs
CE	Chip Enable
OE /VPP	Output Enable/ Program Supply
NC	No Connect

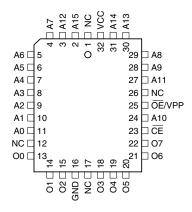
2.1 28-lead PDIP/SOIC Top View



2.3 28-lead TSOP Top View - Type 1



2.2 32-lead PLCC Top View

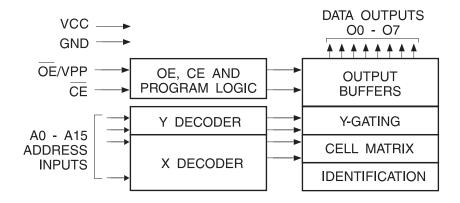


Note: PLCC Package Pins 1 and 17 are Don't Connect.

3. System Considerations

Switching between active and standby conditions via the Chip Enable pin may produce transient voltage excursions. Unless accommodated by the system design, these transients may exceed datasheet limits, resulting in device non-conformance. At a minimum, a 0.1 μF high frequency, low inherent inductance, ceramic capacitor should be utilized for each device. This capacitor should be connected between the V_{CC} and Ground terminals of the device, as close to the device as possible. Additionally, to stabilize the supply voltage level on printed circuit boards with large EPROM arrays, a 4.7 μF bulk electrolytic capacitor should be utilized, again connected between the V_{CC} and Ground terminals. This capacitor should be positioned as close as possible to the point where the power supply is connected to the array.

4. Block Diagram



5. Absolute Maximum Ratings*

Temperature Under Bias55°C to + 125°C
Storage Temperature65°C to + 150°C
Voltage on Any Pin with Respect to Ground2.0V to + 7.0V ⁽¹⁾
Voltage on A9 with Respect to Ground2.0V to + 14.0V ⁽¹⁾
V _{PP} Supply Voltage with Respect to Ground2.0V to + 14.0V ⁽¹⁾

*NOTICE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note: 1. Minimum voltage is -0.6V DC which may undershoot to -2.0V for pulses of less than 20 ns. Maximum output pin voltage is $V_{CC} + 0.75V$ DC which may overshoot to +7.0 volts for pulses of less than 20 ns.



Operating Modes

Mode/Pin	CE	OE/V _{PP}	Ai	Outputs
Read	V _{IL}	V _{IL}	Ai	D _{OUT}
Output Disable	V _{IL}	V _{IH}	X ⁽¹⁾	High Z
Standby	V _{IH}	X ⁽¹⁾	X	High Z
Rapid Program ⁽²⁾	V _{IL}	V _{PP}	Ai	D _{IN}
PGM Inhibit	V _{IH}	V _{PP}	X ⁽¹⁾	High Z
Product Identification ⁽⁴⁾	V _{IL}	V _{IL}	$A9 = V_{H}^{(3)}$ $A0 = V_{IH} \text{ or } V_{IL}$ $A1 - A15 = V_{IL}$	Identification Code

- Notes: 1. X can be V_{IL} or V_{IH} .
 - 2. Refer to Programming Characteristics.
 - 3. $V_H = 12.0 \pm 0.5V$.
 - 4. Two identifier bytes may be selected. All Ai inputs are held low (V_{IL}) , except A9 which is set to V_H and A0 which is toggled low (V_{IL}) to select the Manufacturer's Identification byte and high (V_{IH}) to select the Device Code byte.

DC and AC Operating Conditions for Read Operation

		AT27C512R		
		-45	-70	
Operating Temp.(Case)	Ind.	-40°C - 85°C	-40°C - 85°C	
	Auto.		-40°C - 125°C	
V _{CC} Supply		5V ± 10%	5V ± 10%	

DC and Operating Characteristics for Read Operation

Symbol	Parameter	Condition	Condition			Units
	Innut Load Current	\/ 0\/ +o \/	Ind.		±1	μΑ
I _{LI}	Input Load Current	$V_{IN} = 0V \text{ to } V_{CC}$	Auto.		±5	μΑ
	Output Leakage Current	V 0V to V	Ind.		±5	μΑ
I _{LO}	Output Leakage Current	$V_{OUT} = 0V \text{ to } V_{CC}$	Auto.		±10	μΑ
	V (1) Chandley Cymrant	I_{SB1} (CMOS), $\overline{CE} = V_{CC \pm} 0.3V$	•		100	μΑ
I _{SB}	$V_{CC}^{(1)}$ Standby Current I_{SB2} (TTL), $\overline{CE} = 2.0$ to $V_{CC+} = 0.5$				1	mA
I _{CC}	V _{CC} Active Current	$f = 5 \text{ MHz}, I_{OUT} = 0 \text{ mA}, \overline{CE} = V_{IL}$	f = 5 MHz, I _{OUT} = 0 mA, $\overline{\text{CE}}$ = V _{IL}			mA
V _{IL}	Input Low Voltage					٧
V _{IH}	Input High Voltage		2.0	V _{CC} + 0.5	V	
V _{OL}	Output Low Voltage	I _{OL} = 2.1 mA		0.4	V	
V _{OH}	Output High Voltage	I _{OH} = -400 μA	2.4		V	

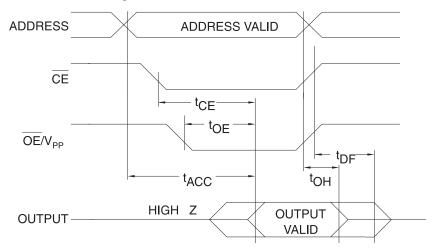
1. V_{CC} must be applied simultaneously with or before \overline{OE}/V_{PP} and removed simultaneously with or after \overline{OE}/V_{PP} . Note:

AC Characteristics for Read Operation

			-45		-70		
Symbol	Parameter	Condition	Min	Max	Min	Max	Units
t _{ACC} ⁽¹⁾	Address to Output Delay	$\overline{CE} = \overline{OE}/V_{PP} = V_{IL}$		45		70	ns
t _{CE} ⁽¹⁾	CE to Output Delay	$\overline{OE}/V_{PP} = V_{IL}$		45		70	ns
t _{OE} ⁽¹⁾	OE/V _{PP} to Output Delay	CE = V _{IL}		20		30	ns
t _{DF} ⁽¹⁾	OE/V _{PP} or CE High to Output Float, Which		20		25	ns	
t _{OH}	Output Hold from Address, $\overline{\text{CE}}$ or $\overline{\text{OE}}/\text{V}_{PP}$ Whichever Occurred First				7		ns

1. See AC Waveforms for Read Operation. Note:

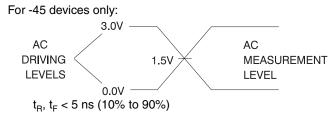
10. AC Waveforms for Read Operation⁽¹⁾



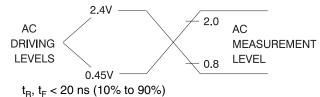
- Notes: 1. Timing measurement reference level is 1.5V for -45 devices. Input AC drive levels are $V_{IL} = 0.0V$ and $V_{IH} = 3.0V$. Timing measurement reference levels for all other speed grades are $V_{OL} = 0.8V$ and $V_{OH} = 2.0V$. Input AC drive levels are $V_{IL} = 0.45V$ and $V_{IH} = 2.4V$.
 - 2. $\overline{\text{OE}}/\text{V}_{PP}$ may be delayed up to t_{CE} t_{OE} after the falling edge of $\overline{\text{CE}}$ without impact on t_{CE} .
 - 3. \overline{OE}/V_{PP} may be delayed up to t_{ACC} t_{OE} after the address is valid without impact on t_{ACC} .
 - 4. This parameter is only sampled and is not 100% tested.
 - 5. Output float is defined as the point when data is no longer driven.



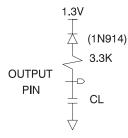
11. Input Test Waveforms and Measurement Levels



For -70 devices:



12. Output Test Load



Note: 1. $C_L = 100 \text{ pF}$ including jig capacitance, except for the -45 devices, where $C_L = 30 \text{ pF}$.

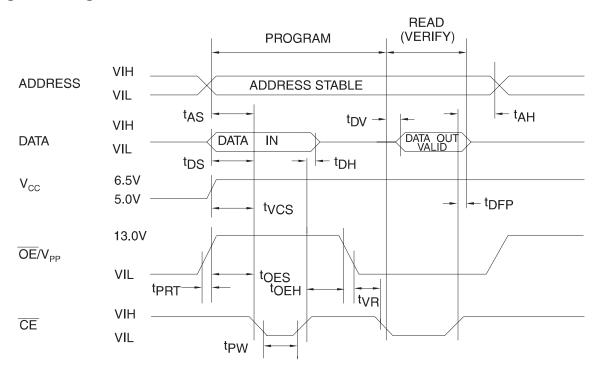
13. Pin Capacitance

 $f = 1 \text{ MHz}, T = 25^{\circ}C^{(1)}$

Symbol	Тур	Max	Units	Conditions
C _{IN}	4	6	pF	$V_{IN} = 0V$
C _{OUT}	8	12	pF	V _{OUT} = 0V

Note: 1. Typical values for nominal supply voltage. This parameter is only sampled and is not 100% tested.

14. Programming Waveforms⁽¹⁾



Notes: 1. The Input Timing Reference is 0.8V for $V_{\rm IL}$ and 2.0V for $V_{\rm IH}$.

2. t_{OE} and t_{DEP} are characteristics of the device but must be accommodated by the programmer.

15. DC Programming Characteristics

 $T_A = 25 \pm 5^{\circ}C, V_{CC} = 6.5 \pm 0.25V, \overline{OE}/V_{PP} = 13.0 \pm 0.25V$

			Limits		
Symbol	Parameter	Test Conditions	Min	Max	Units
I _{LI}	Input Load Current	$V_{IN} = V_{IL}, V_{IH}$		±10	μΑ
V_{IL}	Input Low Level		-0.6	0.8	V
V_{IH}	Input High Level		2.0	V _{CC} + 1	V
V _{OL}	Output Low Voltage	I _{OL} = 2.1 mA		0.4	V
V_{OH}	Output High Voltage	I _{OH} = -400 μA	2.4		V
I _{CC2}	V _{CC} Supply Current (Program and Verify)			25	mA
I _{PP2}	OE/V _{PP} Current	CE = V _{IL}		25	mA
V _{ID}	A9 Product Identification Voltage		11.5	12.5	V



16. AC Programming Characteristics

 $T_A = 25 \pm 5^{\circ}C$, $V_{CC} = 6.5 \pm 0.25V$, $\overline{OE}/V_{PP} = 13.0 \pm 0.25V$

			Lin	nits	
Symbol	Parameter	Test Conditions ⁽¹⁾	Min	Max	Units
t _{AS}	Address Setup Time		2		μs
t _{OES}	ŌE/V _{PP} Setup Time		2		μs
t _{OEH}	ŌĒ/V _{PP} Hold Time	Input Rise and Fall Times	2		μs
t _{DS}	Data Setup Time	(10% to 90%) 20 ns	2		μs
t _{AH}	Address Hold Time	Input Pulse Levels	0		μs
t _{DH}	Data Hold Time	0.45V to 2.4V	2		μs
t _{DFP}	CE High to Output Float Delay(2)]	0	130	ns
t _{VCS}	V _{CC} Setup Time	Input Timing Reference Level 0.8V to 2.0V	2		μs
t _{PW}	CE Program Pulse Width ⁽³⁾	0.07 to 2.07	95	105	μs
t _{DV}	Data Valid from $\overline{CE^{(2)}}$	Output Timing Reference Level		1	μs
t _{VR}	ŌĒ/V _{PP} Recovery Time	0.8V to 2.0V	2		μs
t _{PRT}	OE/V _{PP} Pulse Rise Time During Programming		50		ns

Notes: 1. V_{CC} must be applied simultaneously or before \overline{OE}/V_{PP} and removed simultaneously or after \overline{OE}/V_{PP}

17. Atmel's AT27C512R Integrated Product Identification Code

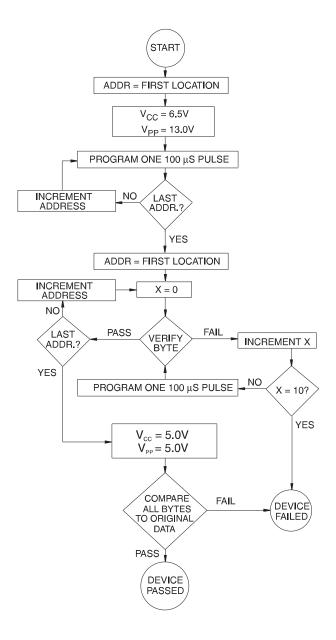
		Pins						Hex		
Codes	Α0	07	O6	O5	04	О3	02	01	00	Data
Manufacturer	0	0	0	0	1	1	1	1	0	1E
Device Type	1	0	0	0	0	1	1	0	1	0D

^{2.} This parameter is only sampled and is not 100% tested. Output Float is defined as the point where data is no longer driven – see timing diagram.

^{3.} Program Pulse width tolerance is 100 μ sec \pm 5%.

18. Rapid Programming Algorithm

A 100 μs \overline{CE} pulse width is used to program. The address is set to the first location. V_{CC} is raised to 6.5V and \overline{OE}/V_{PP} is raised to 13.0V. Each address is first programmed with one 100 μs \overline{CE} pulse without verification. Then a verification/reprogramming loop is executed for each address. In the event a byte fails to pass verification, up to 10 successive 100 μs pulses are applied with a verification after each pulse. If the byte fails to verify after 10 pulses have been applied, the part is considered failed. After the byte verifies properly, the next address is selected until all have been checked. \overline{OE}/V_{PP} is then lowered to V_{IL} and V_{CC} to 5.0V. All bytes are read again and compared with the original data to determine if the device passes or fails.







19. Ordering Information

19.1 Standard Package

t _{ACC}	I _{cc} ((mA)			
(ns)	Active	Standby	Ordering Code	Package	Operation Range
45	20	0.1	AT27C512R-45JI	32J	Industrial
			AT27C512R-45PI	28P6	(-40°C to 85°C)
			AT27C512R-45RI	28R	
			AT27C512R-45TI	28T	
70	20	0.1	AT27C512R-70JI	32J	Industrial
			AT27C512R-70PI	28P6	(-40°C to 85°C)
			AT27C512R-70RI	28R	
			AT27C512R-70TI	28T	
	20	0.1	AT27C512R-70JA	32J	Automotive
			AT27C512R-70PA	28P6	(-40°C to 125°C)
			AT27C512R-70RA	28R	

Note: Refer to PCN# SC042702.

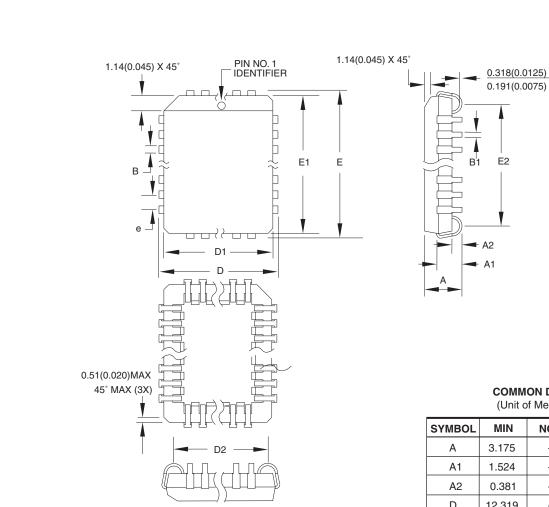
19.2 Green Package (Pb/Halide-free)

t _{ACC}	I _{CC} (mA)				
(ns)	Active	Standby	Ordering Code	Package	Operation Range
45	20	0.1	AT27C512R-45JU	32J	Industrial
			AT27C512R-45PU	28P6	(-40°C to 85°C)
			AT27C512R-45RU	28R	
			AT27C512R-45TU	28T	
70	20	0.1	AT27C512R-70JU	32J	Industrial
			AT27C512R-70PU	28P6	(-40°C to 85°C)
			AT27C512R-70RU	28R	
			AT27C512R-70TU	28T	

	Package Type			
32J	32-Lead, Plastic J-Leaded Chip Carrier (PLCC)			
28P6	28P6 28-Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)			
28R	28-Lead, 0.330" Wide, Plastic Gull Wing Small Outline (SOIC)			
28T	28-Lead, Thin Small Outline Package (TSOP)			

Packaging Information

19.3 32J - PLCC



COMMON DIMENSIONS (Unit of Measure = mm)

E2

MIN NOM MAX NOTE 3.175 3.556 1.524 2.413 0.381 _ 12.319 12.573 D 11.354 11.506 D1 Note 2 D2 9.906 10.922 14.859 Ε 15.113 E1 13.894 14.046 Note 2 E2 12.471 13.487 В 0.660 0.813 B1 0.330 0.533

1.270 TYP

е

10/04/01

Notes:

- 1. This package conforms to JEDEC reference MS-016, Variation AE.
- 2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is .010"(0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
- 3. Lead coplanarity is 0.004" (0.102 mm) maximum.

2325 Orchard Parkway San Jose, CA 95131

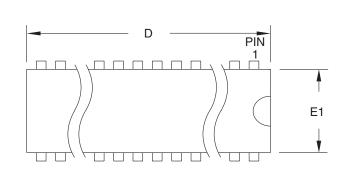
IIILE	
32J, 32-lead,	Plastic J-leaded Chip Carrier (PLCC)

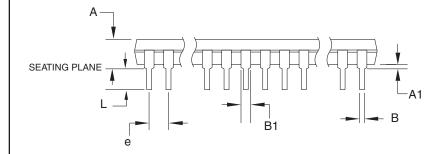
DRAWING NO.	REV.
32J	В

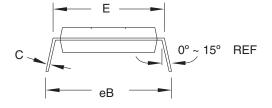




19.4 28P6 - PDIP







Notes:

- 1. This package conforms to JEDEC reference MS-011, Variation AB.
- 2. Dimensions D and E1 do not include mold Flash or Protrusion. Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

COMMON DIMENSIONS

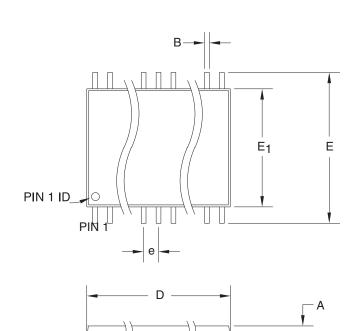
(Unit of Measure = mm)

MIN _	NOM	MAX	NOTE
_			HOIL
	-	4.826	
0.381	_	_	
36.703	_	37.338	Note 2
15.240	1	15.875	
13.462	-	13.970	Note 2
0.356	_	0.559	
1.041	_	1.651	
3.048	_	3.556	
0.203	1	0.381	
15.494	_	17.526	
2.540 TYP			
	36.703 15.240 13.462 0.356 1.041 3.048 0.203	36.703 – 15.240 – 13.462 – 0.356 – 1.041 – 3.048 – 0.203 –	0.381 - - 36.703 - 37.338 15.240 - 15.875 13.462 - 13.970 0.356 - 0.559 1.041 - 1.651 3.048 - 3.556 0.203 - 0.381 15.494 - 17.526

09/28/01

	- -	TITLE	DRAWING NO.	REV.
<u>Alme</u>	2325 Orchard Parkway San Jose, CA 95131	28P6 , 28-lead (0.600"/15.24 mm Wide) Plastic Dual Inline Package (PDIP)	28P6	В

19.5 28R - SOIC





Note: 1. Dimensions D and E1 do not include mold Flash or protrusion. Mold Flash or protrusion shall not exceed 0.25 mm (0.010").

COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
А	2.39	_	2.79	
A1	0.050	_	0.356	
D	18.00	_	18.50	Note 1
E	11.70	_	12.50	
Е	1 8.59	-	8.79	Note 1
В	0.356	-	0.508	
С	0.203	_	0.305	
L	0.94	_	1.27	
е		1.27 TYP		

5/18/2004

С



2325 Orchard Parkway San Jose, CA 95131

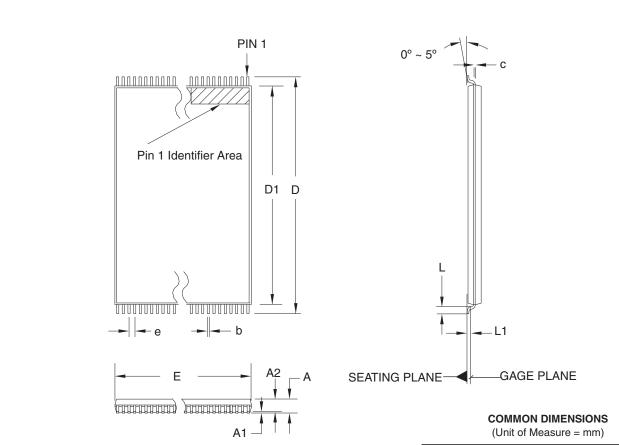
TITLE 28R, 28-lead, 0.330" Body Width, Plastic Gull Wing Small Outline (SOIC)

DRAWING NO. REV. 28R





19.6 28T - TSOP



Notes:

- 1. This package conforms to JEDEC reference MO-183.
- 2. Dimensions D1 and E do not include mold protrusion. Allowable protrusion on E is 0.15 mm per side and on D1 is 0.25 mm per side.
- 3. Lead coplanarity is 0.10 mm maximum.

(0.111.01.11104001.0 11111.)					
SYMBOL	MIN	NOM	MAX	NOTE	
Α	_	_	1.20		
A1	0.05	_	0.15		
A2	0.90	1.00	1.05		
D	13.20	13.40	13.60		
D1	11.70	11.80	11.90	Note 2	
Е	7.90	8.00	8.10	Note 2	
L	0.50	0.60	0.70		
L1	0.25 BASIC				
b	0.17	0.22	0.27		
С	0.10	_	0.21		
е	0.55 BASIC				

12/06/02

TITLE		DRAWING NO.	REV.
\ (\) (\) (\) (\) (\) (\) (\) (\) (\)	, 28-lead (8 x 13.4 mm) Plastic Thin Small Outline kage, Type I (TSOP)	28T	С



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